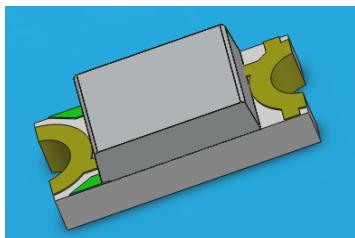


## 1206 Package Chip Infrared LED IR15-21C/L10/TR8



### Features

- Small double-end package
- High reliability
- Low forward voltage
- Good spectral matching to Si photodetector
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

### Descriptions

- IR15-21C/L10/TR8 is an infrared emitting diode in miniature SMD package molded in a water clear plastic with flat top view lens.
- The spectrally device is matched silicon with photodiode and phototransistor.

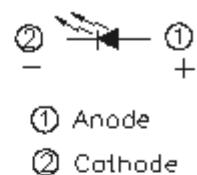
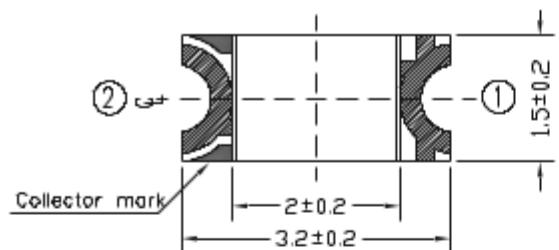
### Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

### Device Selection Guide

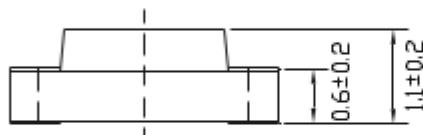
Part Category	Chip Material	Lens Color
IR	GaAlAs	Water Clear

## Package Dimensions

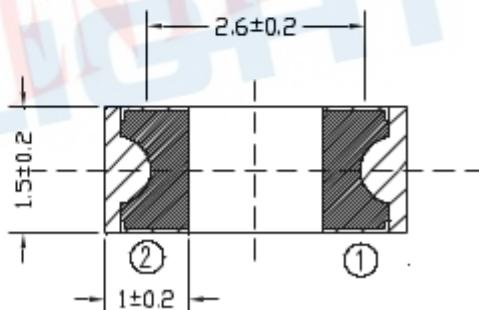
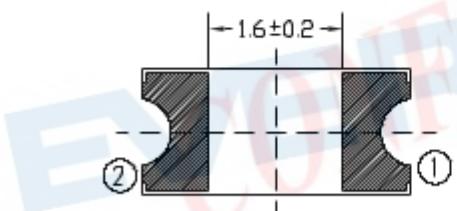


① Anode

② Cathode



For Rollow Soldering (Propose)



**Notes:** 1. All dimensions are in millimeters

2. Tolerances unless dimensions  $\pm 0.1$  mm

3. Suggested pad dimension is just for reference only

Please modify the pad dimension based on individual need

**Absolute Maximum Ratings (Ta=25°C)**

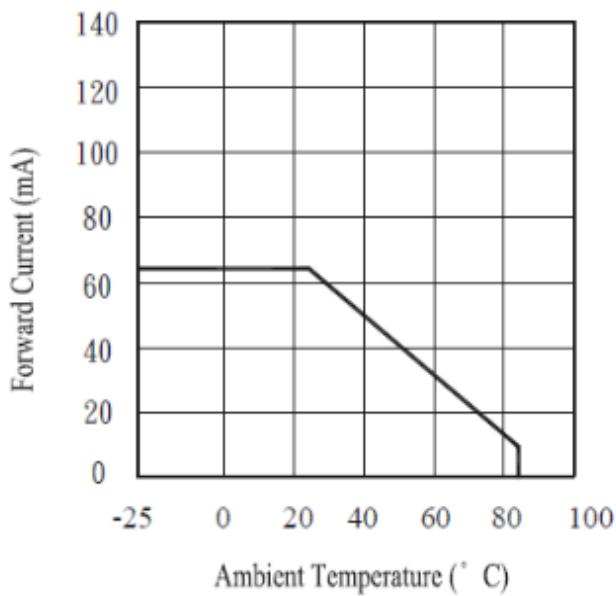
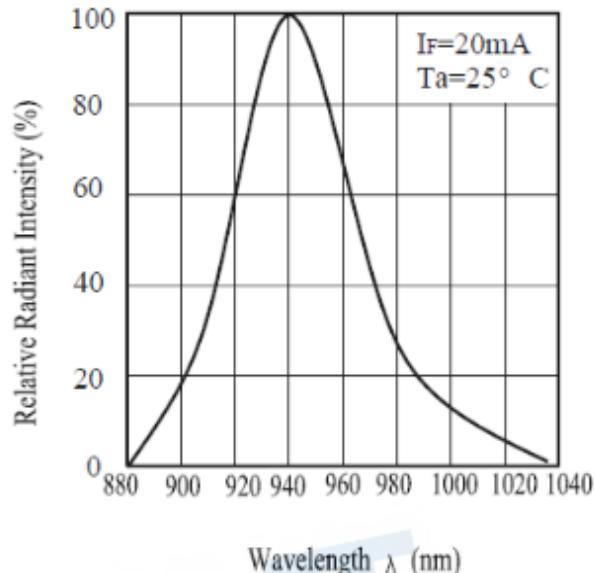
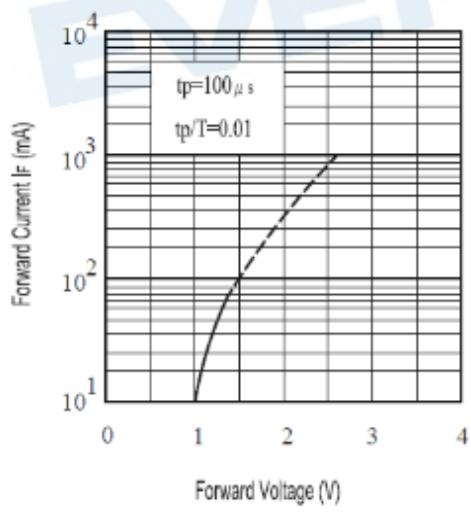
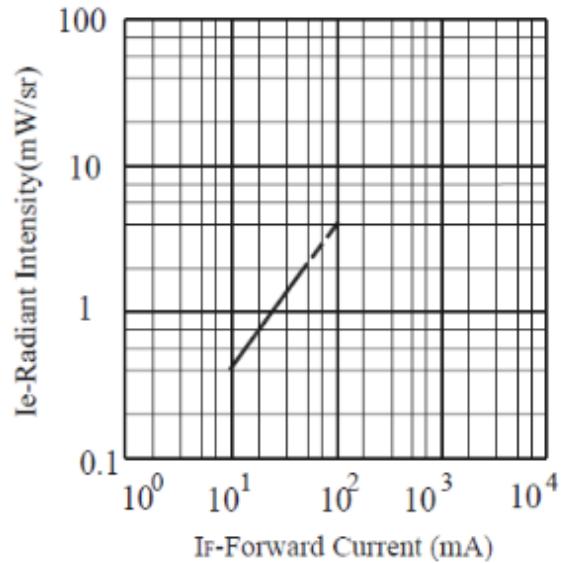
Parameter	Symbol	Rating	Units
Continuous Forward Current	I <sub>F</sub>	65	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>opr</sub>	-25~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	°C
Soldering Temperature *1	T <sub>sol</sub>	260	°C
Power Dissipation at(or below) 25°C Free Air Temperature	P <sub>d</sub>	130	mW

Notes: \*1: Soldering time  $\leq$  5 seconds.

**Electro-Optical Characteristics (Ta=25°C)**

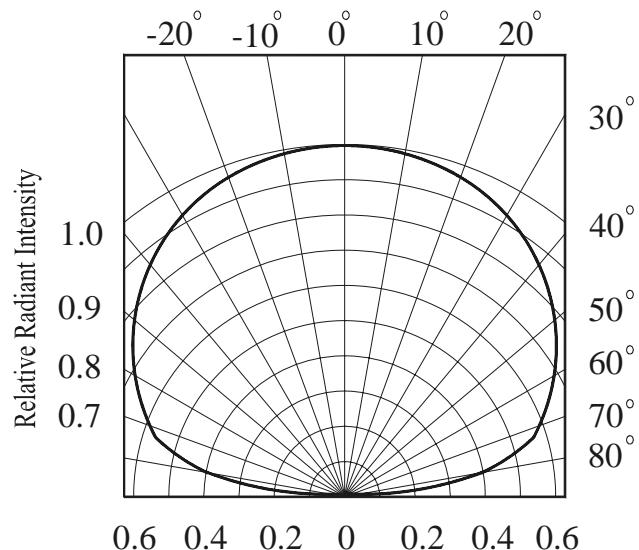
Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	I <sub>E</sub>	I <sub>F</sub> =20mA	0.2	---	---	mW/sr
Peak Wavelength	$\lambda$ p	I <sub>F</sub> =20mA	--	940	--	nm
Spectral Bandwidth	$\Delta \lambda$	I <sub>F</sub> =20mA	--	45	--	nm
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	--	1.2	1.5	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	--	--	10	$\mu$ A
View Angle	2θ 1/2	I <sub>F</sub> =20mA	--	180	--	deg

## Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.  
Ambient TemperatureFig.2 Forward Current  
vs. Forward VoltageFig.3 Forward Current  
vs. Forward VoltageFig.4 Relative Intensity vs.  
Forward Current

## Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs.  
Angular Displacement



## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

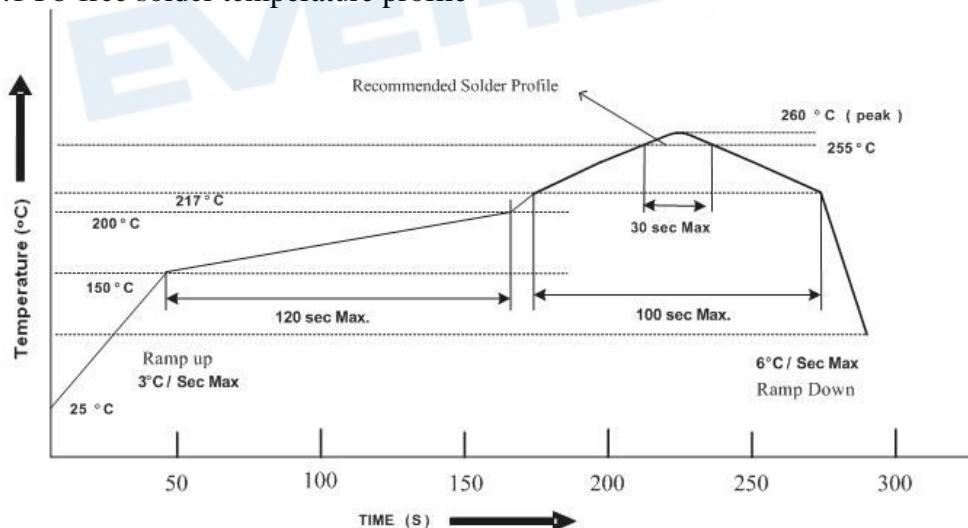
2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment :  $60 \pm 5^\circ\text{C}$  for 48 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

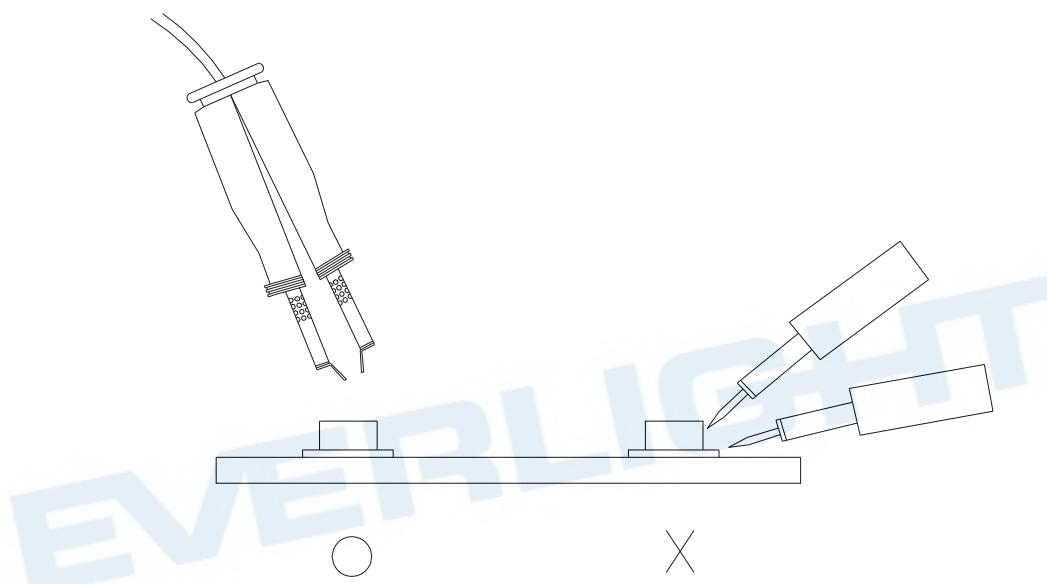
3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

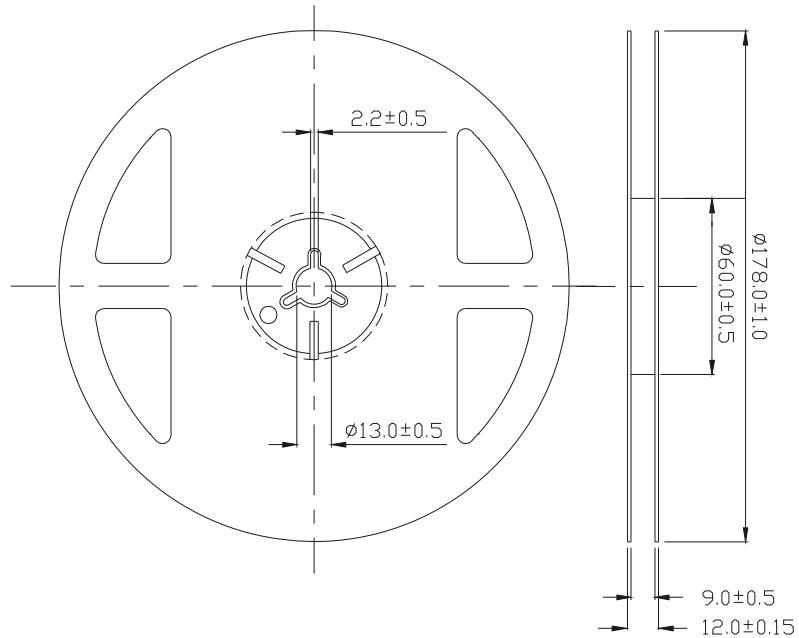
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

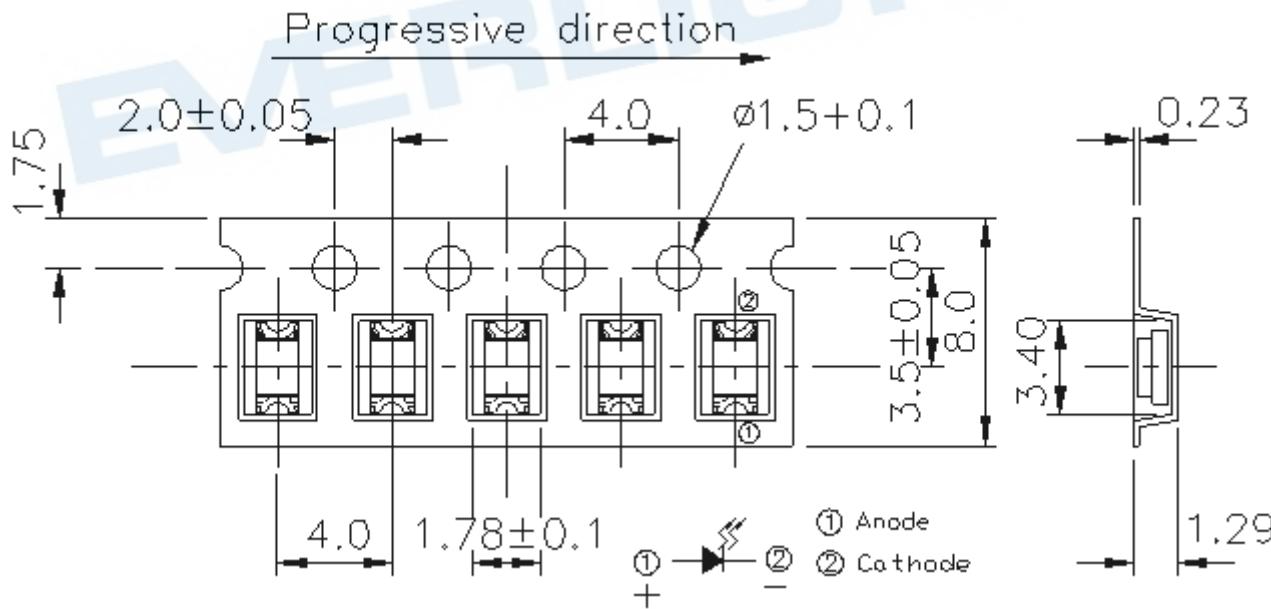


## Package Dimensions



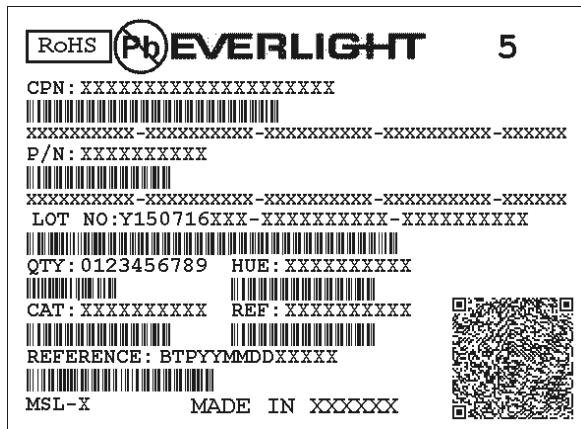
**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  ,Unit = mm

## Carrier Tape Dimensions: (Quantity: 3000 PCS per Reel)



**Note:** The tolerances unless mentioned is  $\pm 0.1\text{mm}$  ,Unit = mm

## Label Form Specification



CPN: Customer's Production Number  
P/N : Production Number  
QTY: Packing Quantity  
CAT: Ranks  
HUE: Peak Wavelength  
REF: Reference  
LOT No: Lot Number  
MSL-X: MSL Level  
Made In: Manufacture place

## Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
4. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without the specific consent of EVERLIGHT.
5. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.

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